

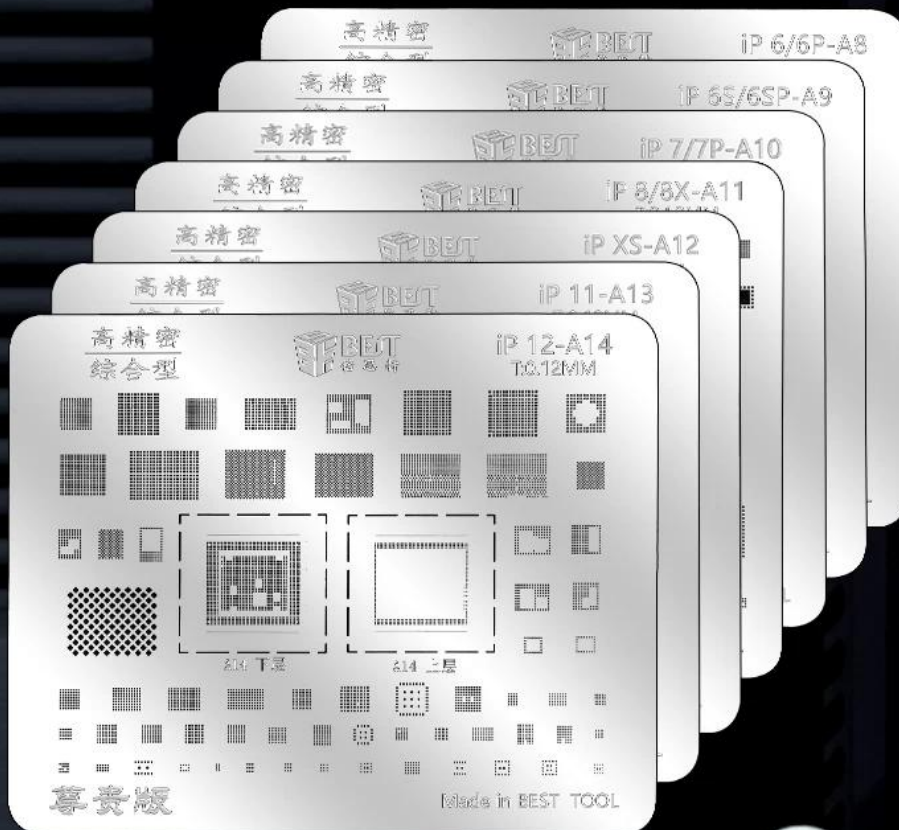


# BGA IC

## SOLDERING REBALLING STENCIL

High toughness

Strong magnetic steel



# Product Usage



<b>Model NO.</b>	BST-iP (A8-A14)	<b>Melting point</b>	700°C
<b>Name</b>	Reballing Stencil	<b>G.W.</b>	25.8g
<b>Material</b>	Strong magnetic steel	<b>Size</b>	141*103*13.1mm





# Four characteristics



Semi-etching process



Cooling hole design



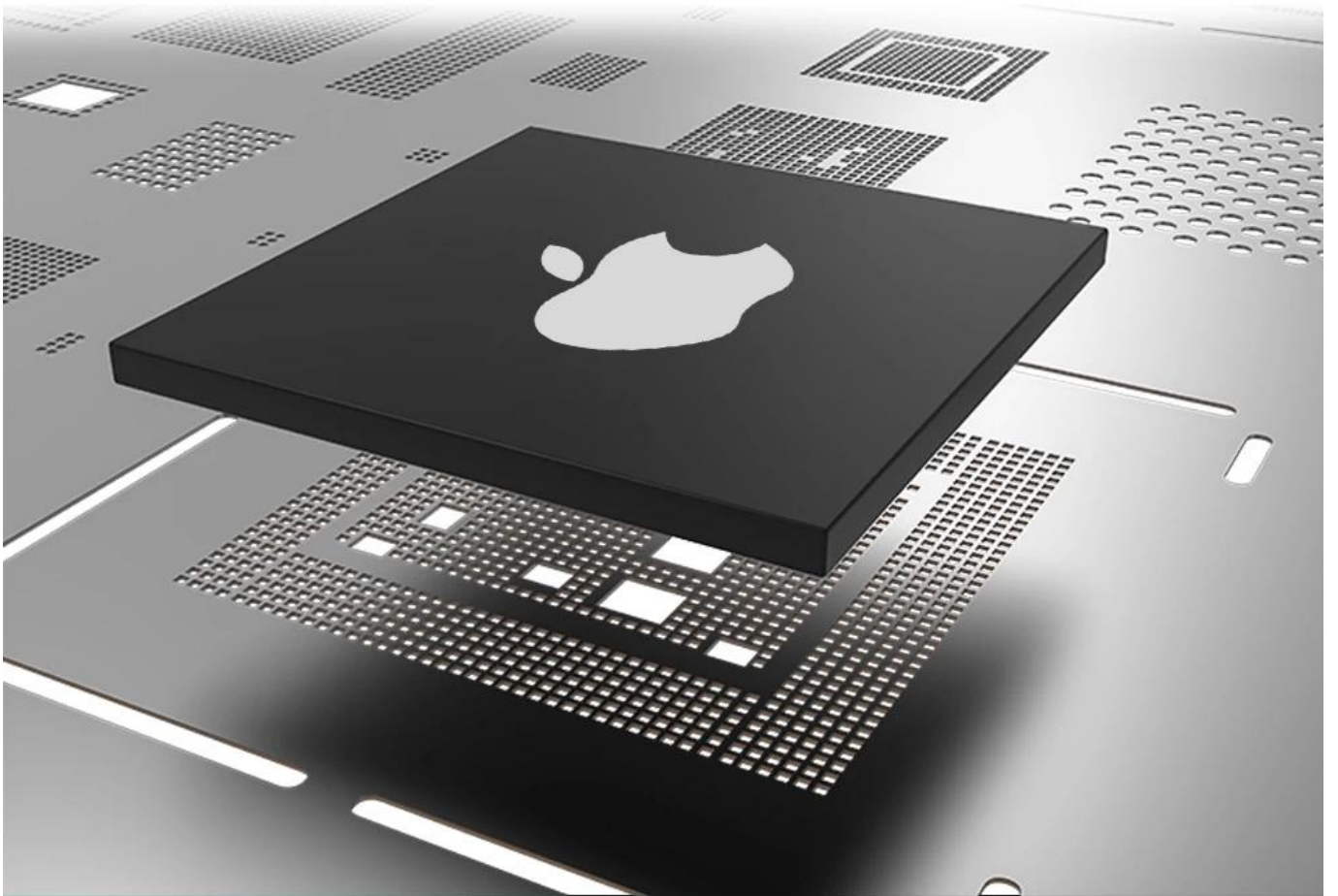
Square hole



Precise alignment

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Easily mounted on the steel mesh to make the chip fit  
more closely with the mesh Therefore.



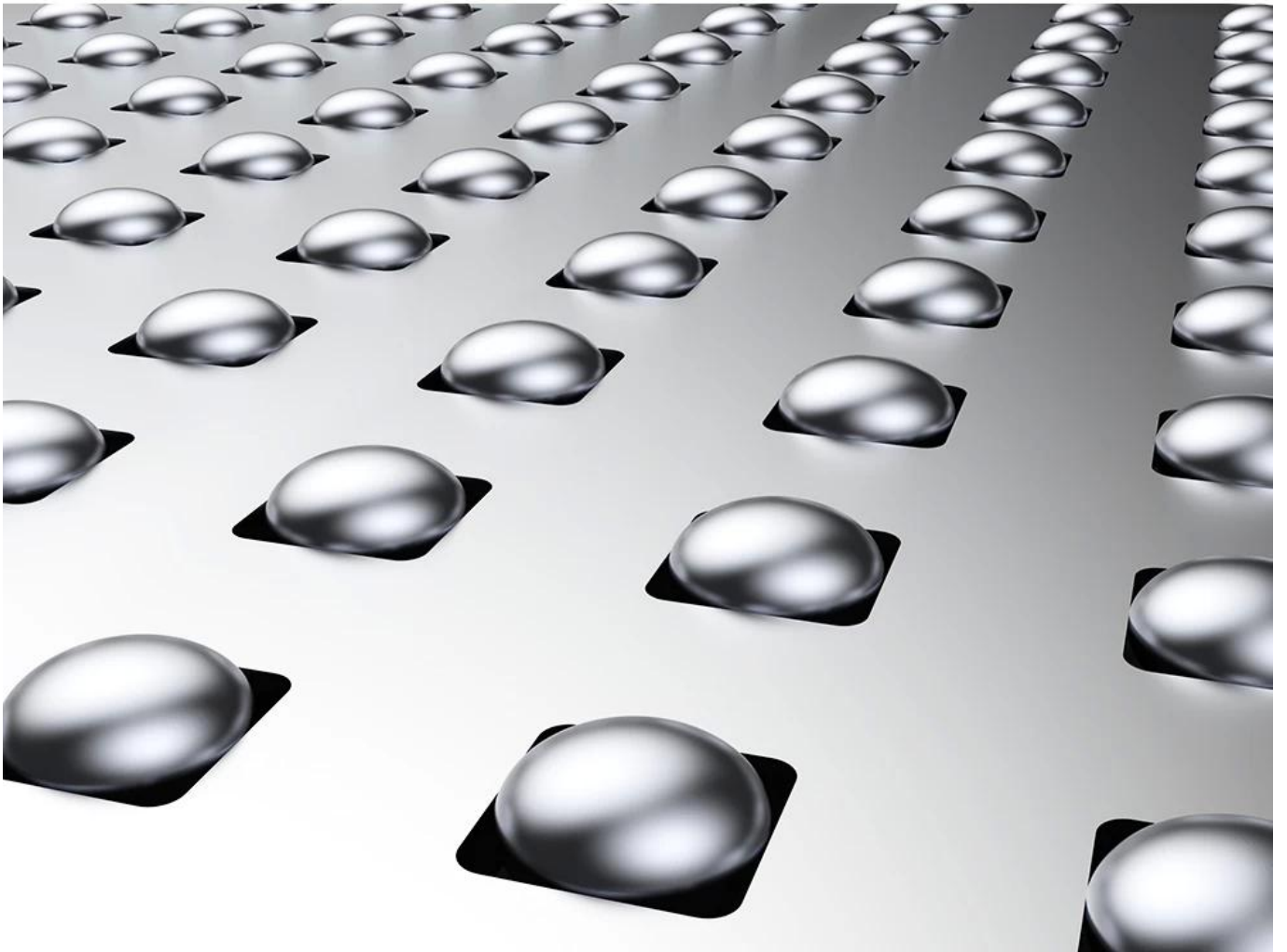
Hard and wear resistant  
vertical hole position, no burr





# Precision Reballing Stencil

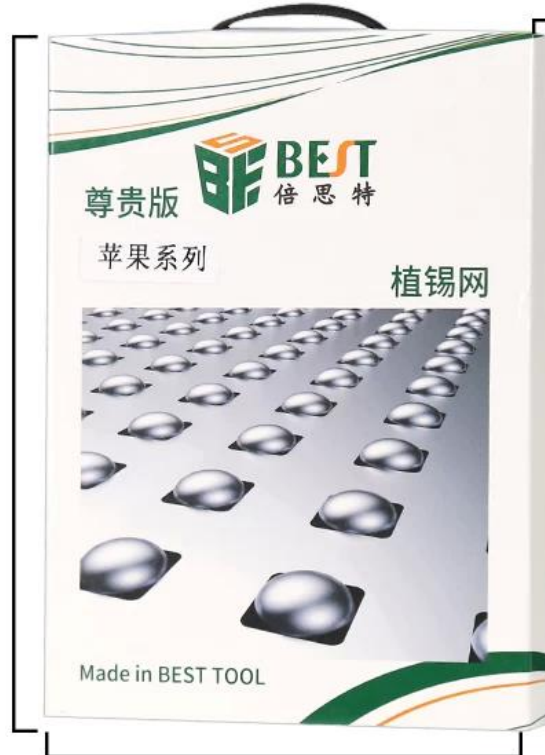
Tin point is neat and tidy



G.W.:25.8G

0.51 in. (13.1mm)

5.55 in. (141mm)



4.05 in. (103mm)